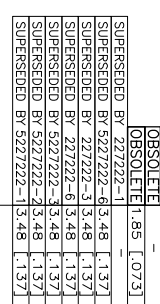


RECOMMENDED PANEL CUTOUT

PCB CONFIGURATION



REV	DATE	BY	APP	DESCRIPTION	MOUNTING	GROUND	CONTACT	CONTACT	CONTACT	VIEW
REV	DATE	BY	APP	DESCRIPTION	PIN PLATING	POST PLATING	POST PLATING	PLATING	MATERIAL	
A	-	-	-	ASSEMBLY	Δ	Δ	Δ	Δ	Δ	1
B	-	-	-	LOCKWASHER	Δ	Δ	Δ	Δ	Δ	2
C	-	-	-	JAM NUT	Δ	Δ	Δ	Δ	Δ	3

- Δ POLYESTER PBT PER MIL-M-24519, TYPE GPT-15F, UL94V-0 RATED, COLOR:NATURAL
- Δ POLYESTER PBT PER MIL-M-24519, TYPE GPT-15F, UL94V-0 RATED, COLOR:BLACK
- Δ POLYMETHYLPENTENE, GENERAL PURPOSE.
- Δ ZINC PER QQ-Z-363.
- Δ PHOSPHOR BRONZE PER QQ-B-750.
- Δ BRASS PER ASTM-B-453.
- Δ BRASS PER ASTM-B-16.
- Δ NICKEL PLATE PER QQ-N-290, 3.81 μm [0.000150] MINIMUM THICK.
- Δ TIN PLATE PER ASTM-B-545, 3.81 μm [0.000150] MINIMUM THICK.
- Δ GOLD PLATE PER MIL-G-45204, 0.76 μm [0.00030] MINIMUM THICK.
- Δ SILVER PLATE PER QQ-S-365, 2.54 μm [0.00100] MINIMUM THICK.
- Δ TIN PLATE PER ASTM-B-545, 3.81 μm [0.000150] MINIMUM THICK.

1 3. SEE INSTRUCTION SHEET 2769.

THIS DRAWING IS A CONTROLLED DOCUMENT

DATE: 10/8-1/2078

WEIGHT: 0.000000

CUSTOMER DRAWING

TE Connectivity

JACK HERRICK, 50 OHM/50SERIES BNC

SCALE: 4:1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)